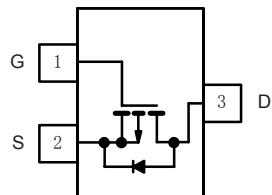
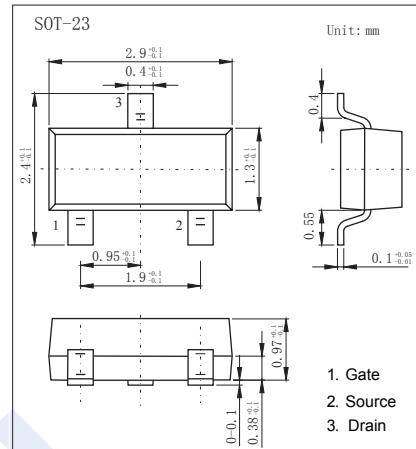


P-Channel MOSFET

SI2333DS-HF (KI2333DS-HF)

■ Features

- V_{DS} (V) = -12V
- I_D = -5.3 A (V_{GS} = -4.5V)
- $R_{DS(ON)} < 32m\Omega$ (V_{GS} = -4.5V)
- $R_{DS(ON)} < 42m\Omega$ (V_{GS} = -2.5V)
- $R_{DS(ON)} < 59m\Omega$ (V_{GS} = -1.8V)
- Pb-Free Package May be Available. The G-Suffix Denotes a Pb-Free Lead Finish



■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	5s	Steady State	Unit
Drain-Source Voltage	V_{DS}	-12		V
Gate-Source Voltage	V_{GS}	± 8		
Continuous Drain Current	I_D	-5.3	-4.1	A
		-4.2	-3.3	
Pulsed Drain Current	I_{DM}	-20		
Power Dissipation	P_D	1.25	0.75	W
		0.8	0.48	
Thermal Resistance.Junction- to-Ambient	R_{thJA}	100	166	°C/W
Thermal Resistance.Junction- to-Foot	R_{thJF}	-	50	
Junction Temperature	T_J	150		°C
Junction Storage Temperature Range	T_{stg}	-55 to 150		

P-Channel MOSFET

SI2333DS-HF (KI2333DS-HF)

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=-250 \mu\text{A}, V_{GS}=0\text{V}$	-12			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-9.6\text{V}, V_{GS}=0\text{V}$			-1	
		$V_{DS}=-9.6\text{V}, V_{GS}=0\text{V}, T_J=55^\circ\text{C}$			-10	uA
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{V}, V_{GS}=\pm 8\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250 \mu\text{A}$	-0.4		-1	V
Static Drain-Source On-Resistance (Note.1)	$R_{DS(on)}$	$V_{GS}=-4.5\text{V}, I_D=-5.3\text{A}$			32	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}, I_D=-4.6\text{A}$			42	
		$V_{GS}=-1.8\text{V}, I_D=-2\text{A}$			59	
On state drain current (Note.1)	$I_{D(on)}$	$V_{GS}=-5\text{V}, V_{DS}=-4.5\text{V}$	-20			A
Forward Transconductance (Note.1)	g_{FS}	$V_{DS}=-5\text{V}, I_D=-5.3\text{A}$		17		S
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}, V_{DS}=-6\text{V}, f=1\text{MHz}$		1100		pF
Output Capacitance	C_{oss}			390		
Reverse Transfer Capacitance	C_{rss}			300		
Total Gate Charge	Q_g	$V_{GS}=-4.5\text{V}, V_{DS}=-6\text{V}, I_D=-5.3\text{A}$		11.5	18	nC
Gate Source Charge	Q_{gs}			1.5		
Gate Drain Charge	Q_{gd}			3.2		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-4.5\text{V}, V_{DS}=-6\text{V}, R_L=6\Omega, R_G=6\Omega, I_D=-1\text{A}$		25	40	ns
Turn-On Rise Time	t_r			45	70	
Turn-Off Delay Time	$t_{d(off)}$			72	110	
Turn-Off Fall Time	t_f			60	90	
Maximum Body-Diode Continuous Current	I_s				-1	A
Diode Forward Voltage	V_{SD}	$I_s=-1\text{A}, V_{GS}=0\text{V}$			-1.2	V

Note.1:Pulse test: $PW \leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

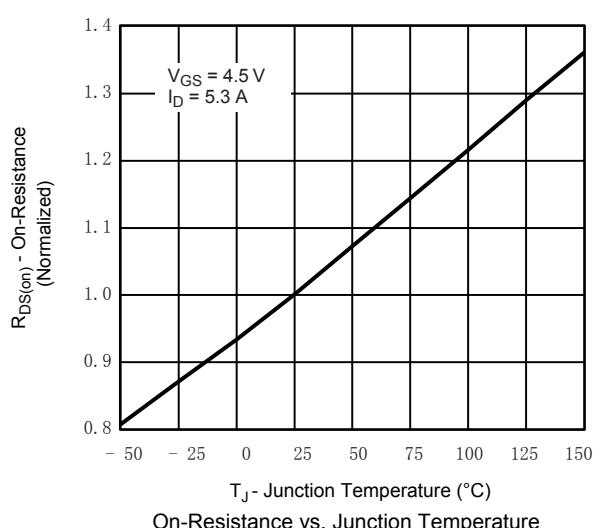
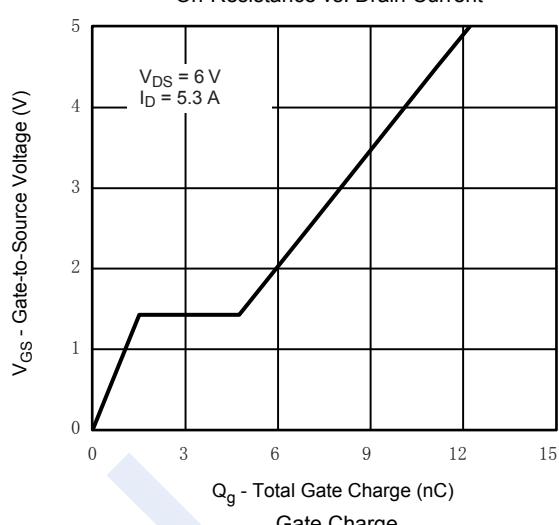
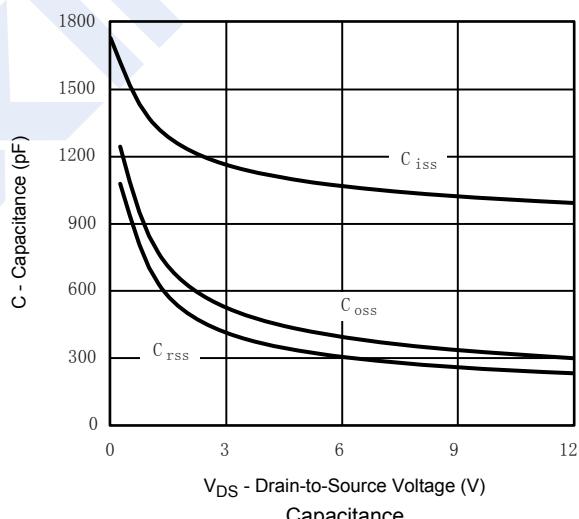
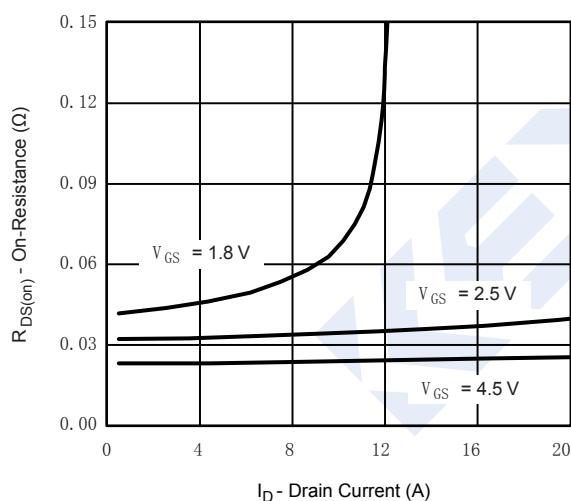
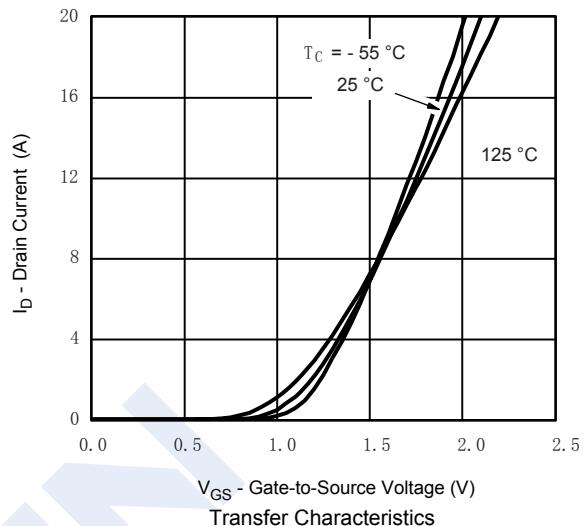
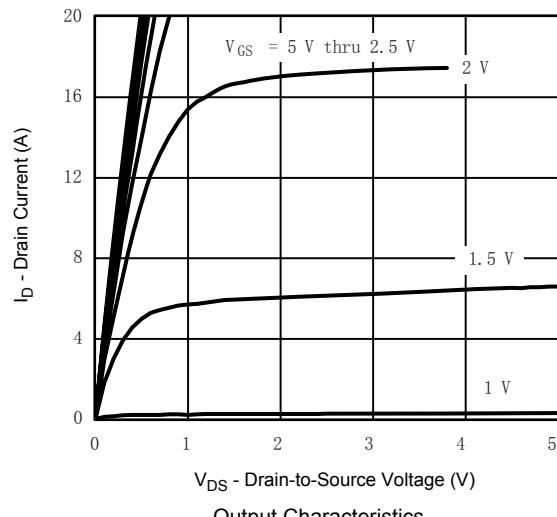
■ Marking

Marking	E3* F
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P-Channel MOSFET

SI2333DS-HF (KI2333DS-HF)

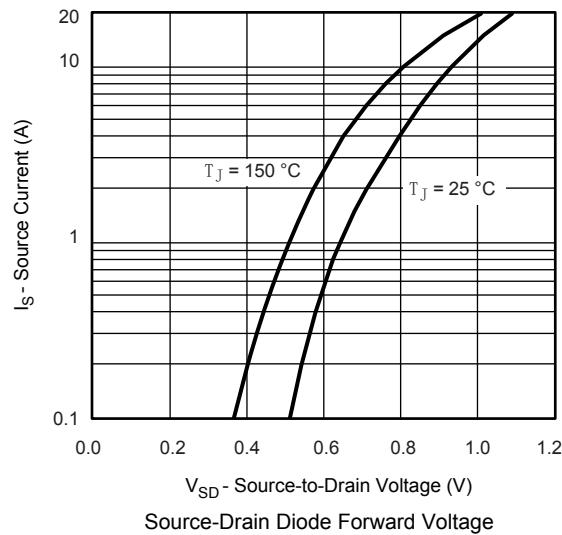
■ Typical Characteristics



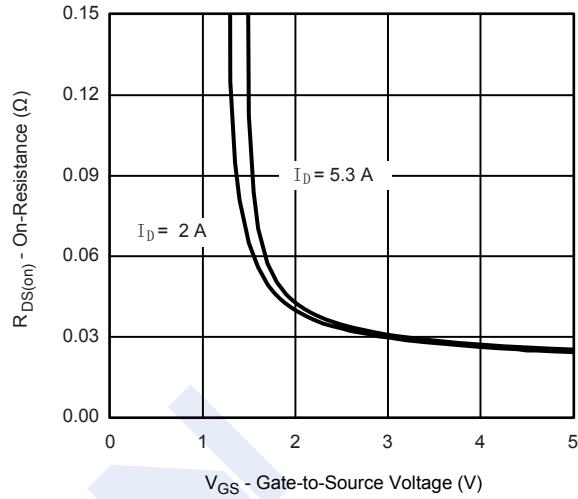
P-Channel MOSFET

SI2333DS-HF (KI2333DS-HF)

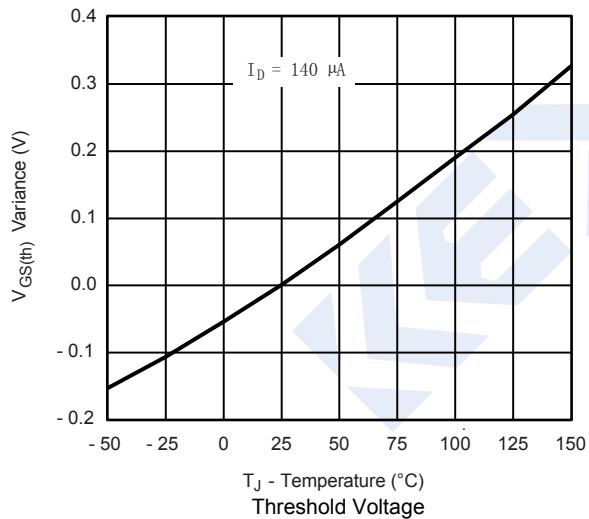
■ Typical Characteristics



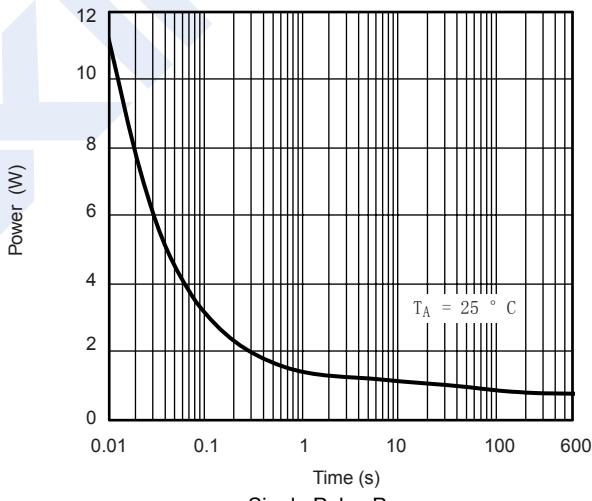
Source-Drain Diode Forward Voltage



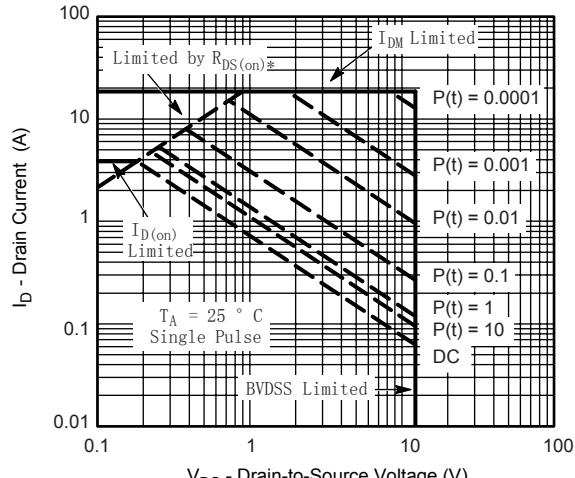
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area

P-Channel MOSFET
SI2333DS-HF (KI2333DS-HF)

■ Typical Characteristics

